WHAT IS CLAIMED IS:

1. A polishing and loading/unloading component module, characterized in comprising: a loading/unloading module in the center and two polishing modules on both sides of the loading/unloading module, wherein the loading/unloading module comprises a loading/unloading table module, the loading/unloading module has a first loading/unloading position (1) and a second loading/unloading position (6)~~two loading/unloading positions~~ in a direction perpendicular to an arrangement direction of the two polishing modules, and the loading/unloading table module ~~can~~ is configured to move back and forth between the first loading/unloading position (1) and the second loading/unloading position (6)~~two loading/unloading positions~~, corresponding to the two polishing modules respectively, and the first loading/unloading position (1) and the second loading/unloading position (6) of the loading/unloading module are respectively provided with a first nozzle module (13) and a second nozzle module (16).

2. The polishing and loading/unloading component module according to claim 1, characterized in that the first loading/unloading position (1) and the second loading/unloading position (6)~~two loading/unloading positions~~ are respectively provided with one loading/unloading table module, corresponding to the two polishing modules.

3. The polishing and loading/unloading component module according to claim 2, characterized in that the loading/unloading module comprises a fixed frame (20), a water tank (11), a first loading/unloading table module (18), a second loading/unloading table module (15), a first loading/unloading table fixed block (19), a second loading/unloading table fixed block (14), a first isolation cover (12), and a second isolation cover (17), the first loading/unloading table module (18) corresponds to a first loading/unloading position (1), the second loading/unloading table module (15) corresponds to a second loading/unloading position (6), the water tank (11), the first loading/unloading table fixed block (19) and the second loading/unloading table fixed block (14) are fixedly installed on the fixed frame (20), and the two isolation covers are fixed

respectively on the corresponding loading/unloading table fixed blocks, so that the lower part of the loading/unloading table module is isolated from liquid, and the first loading/unloading table module (18) and the second loading/unloading table module (15) are respectively fixed on the first loading/unloading table fixed block (19) and the second loading/unloading table fixed block (14), corresponding to the first loading/unloading position (1) and the second loading/unloading position (6).

4. The polishing and loading/unloading component module according to claim 1 or 2, characterized in that, the polishing module comprises a fixed platform, a polishing pad, a polishing head, and a rotating shaft, the polishing pad is located on the fixed platform, and the rotating shaft drives the polishing head to rotate to the loading/unloading position.

5. The polishing and loading/unloading component module according to claim 1, characterized in that, the loading/unloading module comprises a fixed frame (20), a water tank (11), a linear motion module (21), a loading/unloading table module (22), a loading/unloading table fixed block (23), and an isolation cover (24), the water tank (11) and the linear motion module (21) are fixed on the fixed frame (20), the loading/unloading table fixed block (23) is fixed on a sliding block of the linear motion module (21), the loading/unloading table module (22) is fixed on the loading/unloading table fixed block (23), and the lower part of the loading/unloading table fixed block (23) is fixed with the isolation cover (24) to isolate the lower part of the loading/unloading table module from liquid, and the linear motion module (21) makes the loading/unloading table module (22) move back and forth between ~~a~~the first loading/unloading position (1) and ~~a~~the second loading/unloading position (6).

6. The polishing and loading/unloading component module according to claim 1 or 2, characterized in that, ~~a first loading/unloading position (1) and a second loading/unloading position (6) of the loading/unloading module are respectively provided with a first nozzle module (13) and a second nozzle module (16), and~~ both the first nozzle module (13) and the second nozzle module (16) are fixed on a fixed frame (20).

7. The polishing and loading/unloading component module according to claim 6, characterized in that, the first nozzle module (13) and the second nozzle module (16) are respectively arranged at the edges of the first loading/unloading position (1) and the second loading/unloading position (6).

8. The polishing and loading/unloading component module according to claim 1 or 2, characterized in that, the loading/unloading table module ~~can~~ is configured to rise and descend in a vertical direction to complete wafer transfer accompanying with a polishing head.

9. A method for wafer transfer using the polishing and loading/unloading component module according to claim 1, characterized in comprising following steps:

S1: a loading/unloading table module (22) stopping at a first loading/unloading position (1), waiting for a first polishing head (3) corresponding to the first loading/unloading position and carrying a wafer that has been polished in a first stage;

S2: after the first polishing head (3) being transferred to the first loading/unloading position (1), the loading/unloading table module (22) rising to load the wafer, descending and moving to a second loading/unloading position (6);

S3: the first polishing head (3) being cleaned at the position above the first loading/unloading position (1), and the wafer on the loading/unloading table module at the second loading/unloading position (6) being unloaded by a second polishing head (8) to start the polishing in a second stage, and after the second polishing head (8) being transferred above a second polishing pad (9), a robot arm loading a new wafer to be polished to the loading/unloading table module (22);

S4: when the first polishing head (3) corresponding to the first loading/unloading position (1) being cleaned, the loading/unloading table module at the second loading/unloading position (6) moving to below the first polishing head (3) at the first loading/unloading position (1), and then the loading/unloading table module rising, the first polishing head (3) corresponding to the first loading/unloading position (1) loading the wafer to be polished and transferring the wafer to be polished to a polishing area for polishing;

S5: the loading/unloading table module at the first loading/unloading position (1) descending and then moving to the second loading/unloading position (6), while the second polishing head (8) corresponding to the second loading/unloading position (6) moving to the position above the second loading/unloading position (6), the loading/unloading table module rising, and loading the wafer that has been polished in the second stage, and then the loading/unloading table module descending and moving from the second loading/unloading position (6) to the first loading/unloading position (1);

S6: the second polishing head (8) corresponding to the second loading/unloading position (6) being cleaned at the position above the second loading/unloading position (6), while the robot arm removing the wafer that has been polished in the second stage from the loading/unloading table module at the first loading/unloading position (1), and the loading/unloading table module waiting for the wafer that has been polished in the first stage above the first polishing head (3);

S7: after the first polishing head (3) being transferred to the first loading/unloading position (1), the loading/unloading table module rising to load the wafer that has been polished in the first stage, and then moving to the second loading/unloading position (6);

S8: repeating the above steps until all wafers being polished.

~~10. A method for wafer transfer using the polishing and loading/unloading component module according to claim 1, characterized in comprising following steps:~~

~~S1: a loading/unloading table module (22) stopping at a first loading/unloading position (1), waiting for a first polishing head (3) corresponding to the first loading/unloading position and carrying a wafer that has been polished by a first polishing pad;~~

~~S2: after the first polishing head (3) being transferred to the first loading/unloading position (1), the loading/unloading table module (22) rising to load the wafer, descending and moving to a second loading/unloading position (6);~~

~~S3: the first polishing head (3) being cleaned at the position above the first loading/unloading position (1), and a robot arm taking away the wafer on the loading/unloading table module (22) at~~

~~the second loading/unloading position (6) and loading the loading/unloading table module (22) with a new wafer;~~

~~S4: when the first polishing head (3) corresponding to the first loading/unloading position (1) being cleaned, the loading/unloading table module (22) at the second loading/unloading position (6) moving to below the first polishing head (3) at the first loading/unloading position (1), and then the loading/unloading table module (22) rising, the first polishing head (3) corresponding to the first loading/unloading position (1) loading the wafer to be polished and transferring the wafer to be polished to a polishing area for polishing, and then the loading/unloading table module (22) descending;~~

~~S5: repeating the above steps until all wafers being polished.~~

~~11. A method for wafer transfer using the polishing and loading/unloading component module according to claim 1, characterized in comprising following steps:~~

~~S1: a loading/unloading table module (22) stopping at a second loading/unloading position (6), waiting for a second polishing head (8) corresponding to the second loading/unloading position and carrying a wafer that has been polished by a second polishing pad;~~

~~S2: after the second polishing head (8) being transferred to the second loading/unloading position (6), the loading/unloading table module (22) rising to load the wafer, descending and moving to a first loading/unloading position (1);~~

~~S3: the second polishing head (8) being cleaned at the position above the second loading/unloading position (6), and a robot arm taking away the wafer on the loading/unloading table module (22) at the first loading/unloading position (1) and loading the loading/unloading table module (22) with a new wafer;~~

~~S4: When the second polishing head (8) corresponding to the second loading/unloading position (6) being cleaned, the loading/unloading table module (22) at the first loading/unloading position (1) moving to below the second polishing head (8) at the second loading/unloading position (6), and then the loading/unloading table module (22) rising, the second polishing head (8)~~

~~corresponding to the second loading/unloading position (6) loading the wafer to be polished and transferring the wafer to be polished to a polishing area for polishing, and then the loading/unloading table module (22) descending;~~

~~S5: repeating the above steps until all wafers being polished.~~

~~12. A method for wafer transfer using the polishing and loading/unloading component module according to claim 1, characterized in comprising following steps:~~

~~S1: a loading/unloading table module (22) stopping at a loading/unloading position (1, 6), waiting for a polishing head (3, 8) corresponding to the loading/unloading position and carrying a wafer that has been polished;~~

~~S2: after the polishing head (3, 8) being transferred to the loading/unloading position (1, 6), the loading/unloading table module (22) rising to load the wafer, and the polishing head (3, 8) being transferred to a polishing area;~~

~~S3: after a robot arm removing the wafer on the loading/unloading table module (22), the polishing head (3, 8) returning to the loading/unloading position (1, 6), and the polishing head (3, 8) being cleaned;~~

~~S4: after the polishing head (3, 8) being cleaned, the polishing head (3, 8) returning to the polishing area, and the robot arm loading the loading/unloading table module (22) with a new wafer;~~

~~S5: then the loading/unloading table module (22) rising, the polishing head (3, 8) being transferred to the loading/unloading position (1, 6) to load the wafer to be polished and then the loading/unloading table module (22) descending, and the polishing head (3, 8) being transferred to the polishing area for polishing;~~

~~S6: repeating the above steps until all wafers being polished.~~

~~13~~10. A method for wafer transfer using the polishing and loading/unloading component module according to claim 2, characterized in comprising following steps:

S1: a first loading/unloading table module (18), at a first loading/unloading position (1), waiting

for a first polishing head (3) to rotate a wafer that has been polished in a first stage to the first loading/unloading position (1) by a first polishing head rotating shaft (2);

S2: after the wafer that has been polished in the first stage being rotated by the first polishing head rotating shaft (2) to the first loading/unloading position (1), the first loading/unloading table module (18) rising and loading the wafer that has been polished in the first stage;

S3: the first polishing head (3) returning to above a first polishing pad, the first loading/unloading table module (18) descending, and a robot arm starting to remove the wafer that has been polished in the first stage from the first loading/unloading table module and place the wafer which has been polished in the first stage on a second loading/unloading table module (15) at a second loading/unloading position, and the first polishing head (3) returning to the first loading/unloading position (1) for cleaning;

S4: after the first polishing head (3) being cleaned, the first polishing head (3) returning to above the first polishing pad, while the second polishing head (8) returning to the second loading/unloading position (6), the second loading/unloading table module (15) rising, the second polishing head (8) taking away the wafer that has been polished in the first stage, the first loading/unloading table module (18) descending, and the second polishing head (8) returning to above a second polishing pad for polishing, and simultaneously, the robot arm placing an unpolished wafer on the first loading/unloading table module (18) at the first loading/unloading position;

S5: the first polishing head (3) rotating to the first loading/unloading position (1) to remove the wafer to be polished and then starting polishing, and after the polishing of the second polishing head (8) being completed, the second polishing head rotating to the second loading/unloading position (6) to place the wafer that has been polished in a second stage on the second loading/unloading table module (15), and then rotating back to the second polishing pad (9), and the robot arm taking away the polished wafer;

S6: the second polishing head (8) rotating back to the second loading/unloading position (6) for

cleaning, and after being cleaned, the second polishing head (8) returning to the position above the second polishing pad (9), and the first loading/unloading table module (18) waiting for the first polishing head to rotate the wafer that has been polished in the first stage to the first loading/unloading position from by the first polishing head rotating shaft;

S7: repeating the above steps until all wafers being polished.

~~14. A method for wafer transfer using the polishing and loading/unloading component module according to claim 2, characterized in comprising following steps:~~

~~S1: a loading/unloading table module (18, 15), at a loading/unloading position (1, 6), waiting for a polishing head (3, 8) to rotate a polished wafer to the loading/unloading position (1, 6) by a polishing head rotating shaft;~~

~~S2: after the polishing head (3, 8) being transferred to the loading/unloading position (1, 6), the loading/unloading table module (18, 15) rising and loading the polished wafer;~~

~~S3: the polishing head (3, 8) returning to a polishing area, a robot arm starting to take away the polished wafer from the loading/unloading table module (18, 15), and the polishing head (3, 8) returning to the loading/unloading position (1, 6) for cleaning;~~

~~S4: after cleaning, the polishing head (3, 8) returning to the polishing area, and the robot arm loading the loading/unloading table module (18, 15) with a new wafer to be polished;~~

~~S5: then the loading/unloading table module (18, 15) rising, the polishing head (3, 8) being transferred to the loading/unloading position (1, 6) to load the wafer to be polished, and transferred to the polishing area for polishing, and the loading/unloading table module (18, 15) descending;~~

~~S6: repeating the above steps until all wafers being polished.~~